

### AMENDMENTS TO THE CLAIMS

1-8. (Canceled)

9. (Previously presented) A manufacturing method of laser processed parts by using a protective sheet for laser processing having at least an adhesive layer on a base material, with the density of the base material of  $1.1 \text{ g/cm}^3$  or more, comprising a step of adhering an adhesive layer of the protective sheet for laser processing to the incident side of laser beam of a workpiece, a step of processing the protective sheet for laser processing and workpiece by irradiating with laser beam, and a step of peeling off the protective sheet for laser processing from the workpiece after processing,

wherein said base material comprises a base polymer and a filler, said filler being selected from the group consisting of a colorant, a pigment, a dye, gold, copper, platinum, silver, fine metal particles, metal colloids, carbon particles, and inorganic particles,

wherein said filler is 2-20 parts by weight per 100 parts of the base polymer, and

wherein the workpiece is any one of sheet material, circuit board, semiconductor wafer, metal substrate, semiconductor laser light emitting or photo detecting element board, MEMS board, and semiconductor package.

10. (Previously presented) The manufacturing method of claim 14, wherein the ratio of extinction coefficient at ultraviolet region wavelength  $\lambda$  of the base material to extinction coefficient at ultraviolet region wavelength  $\lambda$  of metal material (extinction coefficient ratio=extinction coefficient at ultraviolet region wavelength  $\lambda$  of base material of protective sheet for laser processing/extinction coefficient at ultraviolet region wavelength  $\lambda$  of metal material) is 1 or more.

11. (Previously presented) The manufacturing method of claim 14, wherein the extinction coefficient at ultraviolet region wavelength  $\lambda$  of the base material is  $20 \text{ cm}^{-1}$  or more.

12. (Original) The manufacturing method of laser processed parts of claim 10 or 11, wherein the ultraviolet region wavelength  $\lambda$  is 355 nm.

13. (Previously presented) The manufacturing method of claim 14, wherein the ratio of density of the base material to density of metal material (density ratio=density of base material of protective sheet for laser processing/density of metal material) is 1 or more.

14. (Previously presented) A manufacturing method of laser processed parts by using a protective sheet for laser processing having at least an adhesive layer on a base material, with the density of the base material of  $1.1 \text{ g/cm}^3$  or more, comprising a step of adhering an adhesive layer of the protective sheet for laser processing to the incident side of laser beam of metal material, a step of processing the protective sheet for laser processing and metal material by irradiating with laser beam, and a step of peeling off the protective sheet for laser processing from the metal material after processing,

wherein said base material comprises a base polymer and a filler, said filler being selected from the group consisting of a colorant, a pigment, a dye, gold, copper, platinum, silver, fine metal particles, metal colloids, carbon particles, and inorganic particles, and

wherein said filler is 2-20 parts by weight per 100 parts of the base polymer.

15. (Previously presented) The manufacturing method of claim 14, wherein the ratio of tensile strength of protective sheet for laser processing to tensile strength of metal material (tensile strength ratio=tensile strength of protective sheet for laser processing/tensile strength of metal material) is 1 or more.

16. (Previously presented) The manufacturing method of claim 14, wherein the protective sheet has a tensile strength of 100 MPa or more.

17. (Previously presented) The manufacturing method of claim 14, wherein the specific heat of the base material to specific heat of metal material (specific heat ratio=specific heat of base material of protective sheet for laser processing/specific heat of metal material) is less than 1.

18. (Canceled)

19. (Previously presented) A manufacturing method of laser processed parts by using a protective sheet for laser processing having at least an adhesive layer on a base material, with the density of the base material of  $1.1 \text{ g/cm}^3$  or more, comprising a step of adhering an adhesive layer of the protective sheet for laser processing to the incident side of laser beam of a workpiece, a step of processing the protective sheet for laser processing and workpiece by irradiating with laser beam, and a step of peeling off the protective sheet for laser processing from the workpiece after processing,

wherein said base material comprises a base polymer and a filler, said filler being selected from the group consisting of a colorant, a pigment, a dye, gold, copper, platinum, silver, fine metal particles, metal colloids, carbon particles, and inorganic particles,

wherein said filler is 2-20 parts by weight per 100 parts of the base polymer, and

wherein the workpiece is semiconductor wafer or metal substrate.

20. (Previously presented) A manufacturing method of laser processed parts by using a protective sheet for laser processing having at least an adhesive layer on a base material, with 1 or more of ratio of refractive index at wavelength 546 nm of the base material to refractive index at wavelength 546 nm of organic workpiece (refractive index ratio=refractive index at wavelength 546 nm of base material of protective sheet for laser processing/refractive index at wavelength 546 nm of organic workpiece), comprising a step of adhering an adhesive layer of the protective sheet for laser processing to the incident side of laser beam of the organic workpiece, a step of processing the protective sheet for laser processing and organic workpiece by irradiating with laser beam, and a step of peeling off the protective sheet for laser processing from the organic workpiece after processing,

wherein said base material comprises a base polymer and a filler, said filler being selected from the group consisting of a colorant, a pigment, a dye, gold, copper, platinum, silver, fine metal particles, metal colloids, carbon particles, and inorganic particles, and

wherein said filler is 2-20 parts by weight per 100 parts of the base polymer.

21. (Previously presented) A manufacturing method of laser processed parts by using a protective sheet for laser processing having at least an adhesive layer on a base material, with refractive index at wavelength 546 nm of the base material of 1.53 or more, comprising a step of adhering an adhesive layer of the protective sheet for laser processing to the incident side of laser beam of inorganic workpiece, a step of processing the protective sheet for laser processing and inorganic workpiece by irradiating with laser beam, and a step of peeling off the protective sheet for laser processing from the inorganic workpiece after processing,

wherein said base material comprises a base polymer and a filler, said filler being selected from the group consisting of a colorant, a pigment, a dye, gold, copper, platinum, silver, fine metal particles, metal colloids, carbon particles, and inorganic particles, and

wherein said filler is 2-20 parts by weight per 100 parts of the base polymer.

22. (Previously presented) A manufacturing method of laser processed parts by using a protective sheet for laser processing having at least an adhesive layer on a base material, with less than 1 of total coupling energy ratio (total coupling energy ratio=total coupling energy A equivalent to minimum value among sums of coupling energy of one carbon atom in resin component for composing a base material and other atom coupled with the carbon atom/total coupling energy B equivalent to minimum value among sums of coupling energy of one carbon atom in material component for composing an organic workpiece and other atom coupled with the carbon atom, comprising a step of adhering an adhesive layer of protective sheet for laser processing to the incident side of laser beam of the organic workpiece, a step of processing the protective sheet for laser processing and organic workpiece by irradiating with laser beam, and a step of peeling off the protective sheet for laser processing from the organic workpiece after processing,

wherein said base material comprises a base polymer and a filler, said filler being selected from the group consisting of a colorant, a pigment, a dye, gold, copper, platinum, silver, fine metal particles, metal colloids, carbon particles, and inorganic particles, and wherein said filler is 2-20 parts by weight per 100 parts of the base polymer.

23. (Previously presented) A manufacturing method of laser processed parts by using a protective sheet for laser processing having at least an adhesive layer on a base material, with total coupling energy A equivalent to minimum value among sums of coupling energy of one carbon atom in resin component for composing a base material and other atom coupled with the carbon atom of less than 800 kJ/mol, comprising a step of adhering an adhesive layer of protective sheet for laser processing to the incident side of laser beam of inorganic workpiece, a step of processing the protective sheet for laser processing and inorganic workpiece by irradiating with laser beam, and a step of peeling off the protective sheet for laser processing from the inorganic workpiece after processing,

wherein said base material comprises a base polymer and a filler, said filler being selected from the group consisting of a colorant, a pigment, a dye, gold, copper, platinum, silver, fine metal particles, metal colloids, carbon particles, and inorganic particles, and wherein said filler is 2-20 parts by weight per 100 parts of the base polymer.

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24. (Previously presented) The manufacturing method of laser processed parts of claim 21 or 23, wherein the inorganic workpiece is any one of circuit board, semiconductor wafer, glass substrate, ceramic substrate, metal substrate, semiconductor laser light emitting or photo detecting element board, MEMS board, and semiconductor package.

25. (Previously presented) The manufacturing method of laser process parts of claim 14, wherein the base material contains aromatic polymer or silicone rubber.

26-27. (Canceled)